



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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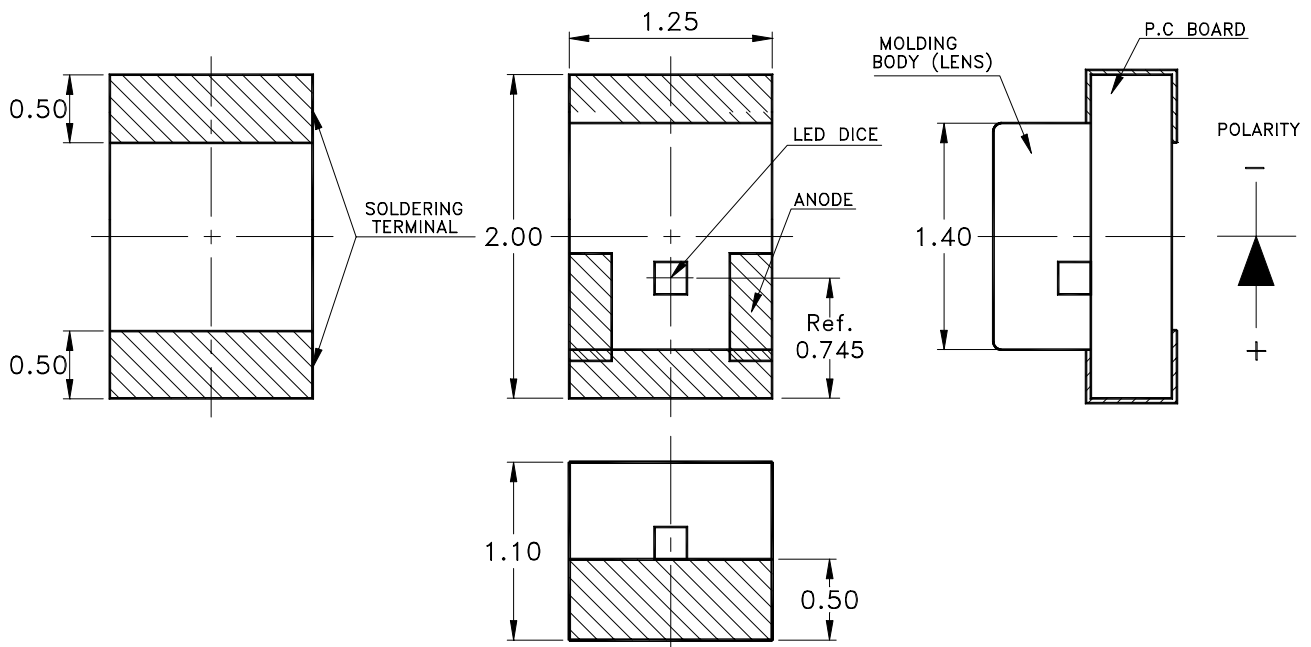


Property of Lite-On Only

Features

- * Package in 8mm tape on 7" diameter reels.
- * Compatible with automatic placement equipment.
- * Compatible with infrared and vapor phase reflow solder process.
- * EIA STD package.
- * I.C. compatible.

Package Dimensions



| Part no. | Lens | Source Color |
|--------------|-------------|--------------------|
| LTST-C170CKT | Water Clear | AlGaAs on GaAs Red |

Notes:

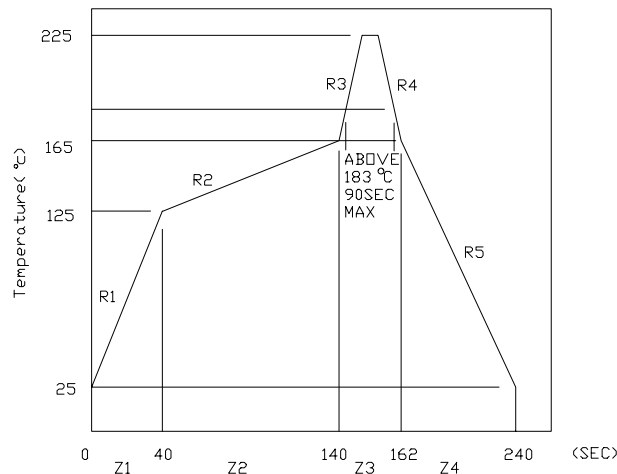
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.1\text{mm}$ (.004") unless otherwise noted.

Property of Lite-On Only

Absolute Maximum Ratings At Ta=25°C

| Parameter | LTST-C170CKT | Unit |
|--|---------------------|-------|
| Power Dissipation | 100 | mW |
| Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width) | 200 | mA |
| Continuous Forward Current | 40 | mA |
| Derating Linear From 50°C | 0.8 | mA/°C |
| Reverse Voltage | 5 | V |
| Operating Temperature Range | -55°C to + 85°C | |
| Storage Temperature Range | -55°C to + 85°C | |
| Wave Soldering Condition | 260°C For 5 Seconds | |
| Infrared Soldering Condition | 260°C For 5 Seconds | |
| Vapor Phase Soldering Condition | 215°C For 3 Minutes | |

Suggest IR Reflow Condition :





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Electrical Optical Characteristics At Ta=25°C

| Parameter | Symbol | Part No. LTST- | Min. | Typ. | Max. | Unit | Test Condition |
|--------------------------|------------------|-------------------|------|------|------|---------|------------------------------|
| Luminous Intensity | IV | C170CKT | 2.8 | 10.0 | | mcd | IF = 10mA Note 1 |
| Viewing Angle | 2θ 1/2 | C170CKT | | 130 | | deg | Note 2 (Fig.6) |
| Peak Emission Wavelength | λ Peak | C170CKT | | 660 | | nm | Measurement @Peak (Fig.1) |
| Dominant Wavelength | λ d | C170CKT | | 638 | | nm | Note 3 |
| Spectral Line Half-Width | $\Delta \lambda$ | C170CKT | | 20 | | nm | |
| Forward Voltage | VF | C170CKT | | 1.8 | 2.4 | V | IF = 20mA |
| Reverse Current | IR | C170CKT | | | 100 | μ A | VR = 5V |
| Capacitance | C | C170CKT | | 30 | | PF | VF = 0 f = 1MHZ |

Notes:

1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
3. The dominant wavelength, λ d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device



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Bin Code List

| Luminous Intensity | | Unit : mcd @10mA |
|--------------------|------|------------------|
| Bin Code | Min. | Max. |
| H | 2.8 | 4.5 |
| J | 4.5 | 7.1 |
| K | 7.1 | 11.2 |
| L | 11.2 | 18.0 |
| M | 18.0 | 28.0 |

Tolerance on each Intensity bin is +/-15%

Property of Lite-On Only

Typical Electrical / Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

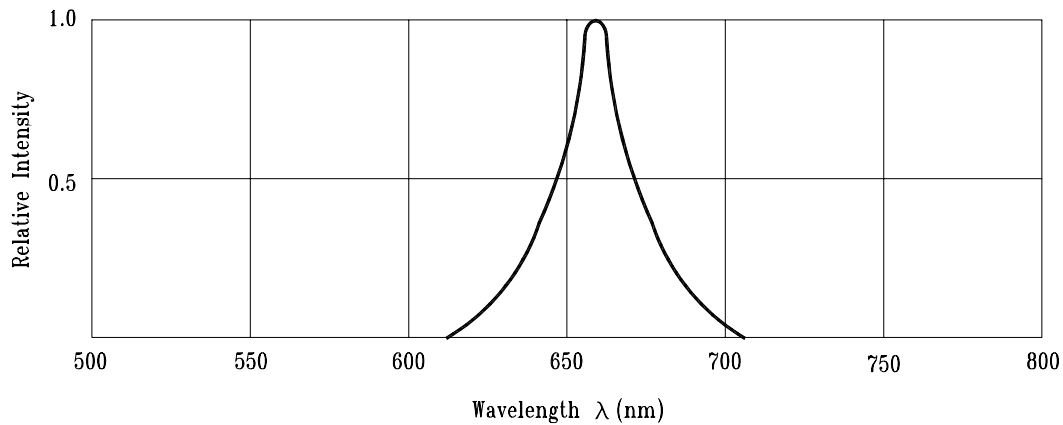


Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

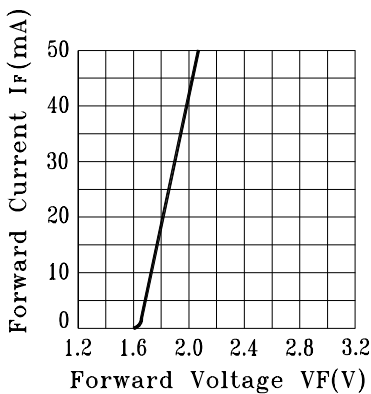


Fig.2 FORWARD CURRENT VS. FORWARD VOLTAGE

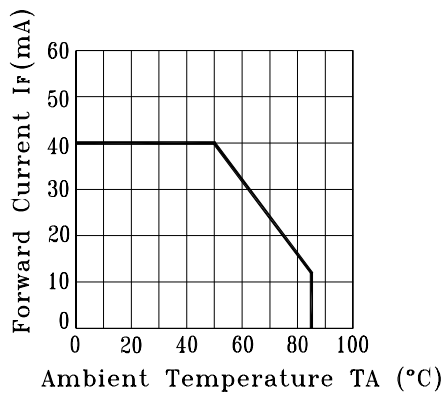


Fig.3 FORWARD CURRENT DERATING CURVE

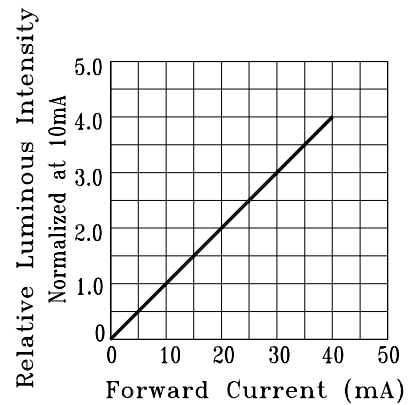


Fig.4 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

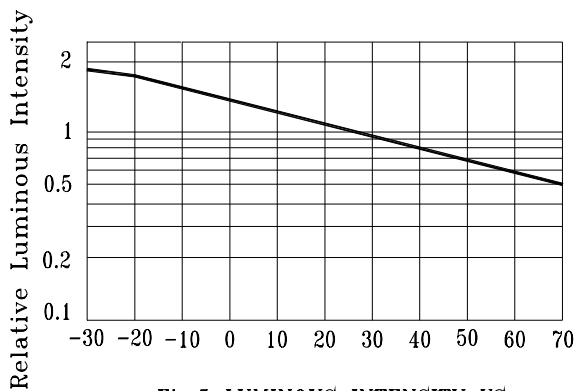


Fig.5 LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE.

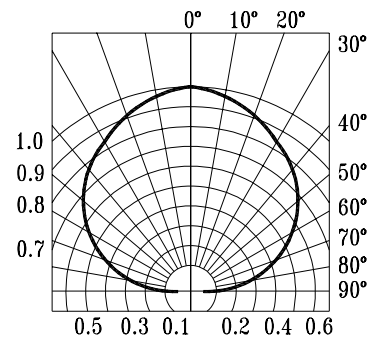


Fig.6 SPATIAL DISTRIBUTION

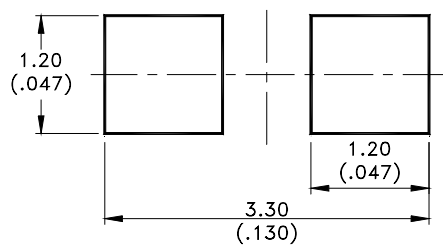
Property of Lite-On Only

Cleaning

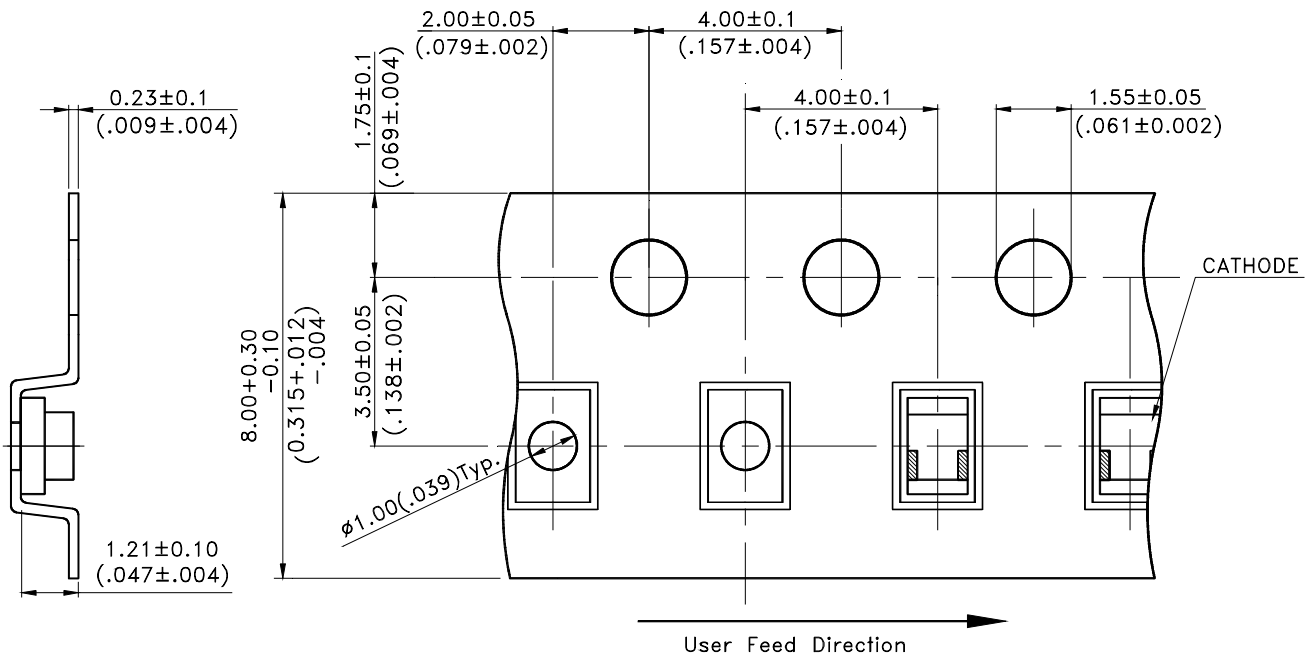
Do not use unspecified chemical liquid to clean LED they could harm the package.

If clean is necessary, immerse the LED in ethyl alcohol or in isopropyl alcohol at normal temperature for less one minute.

Suggest Soldering Pad Dimensions

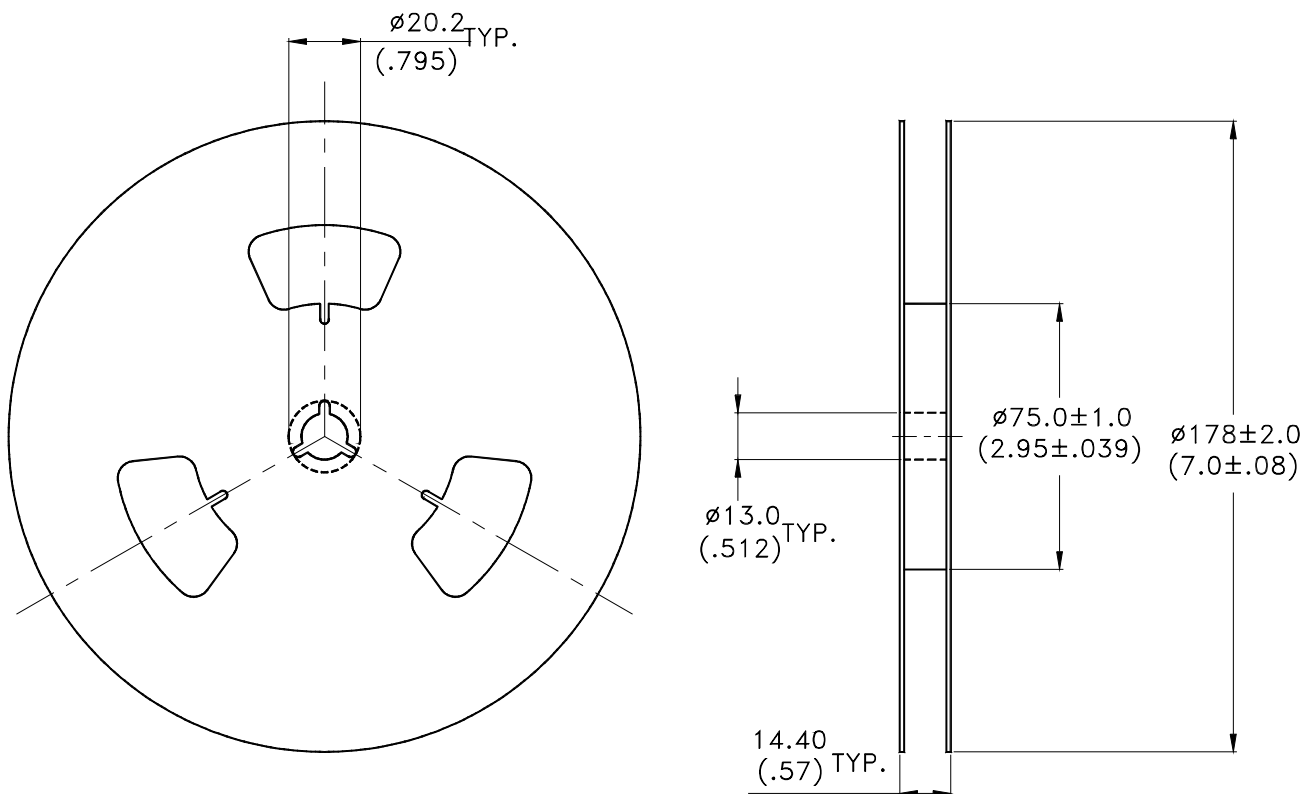


Package Dimensions Of Tape And Reel



1. All dimensions are in millimeters (inches).

Property of Lite-On Only



Notes:

1. Empty component pockets sealed with top cover tape.
2. 7 inch reel-3000 pieces per reel.
3. The maximum number of consecutive missing lamps is two.
4. In accordance with ANSI/EIA 481-1-A-1994 specifications.

Property of Lite-On Only

CAUTIONS

1. Application limitation

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application.) Consult Liteon's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2. Storage

Before opening the package : The LEDs should be kept at 30°C or less and 85%RH or less. The LEDs should be used within a year.

After opening the package : The LEDs should be kept at 30°C or less and 70%RH or less. The LEDs should be soldered within 168 hours(7 days) after opening the package.

Please avoid rapid transitions in ambient temperature in high humidity environments where condensation may occur.

3. Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED.

4. Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering condition

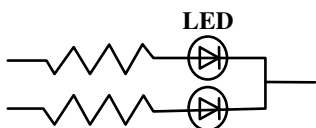
| Reflow soldering | | Soldering iron | | Wave soldering | |
|------------------|---------------|----------------|-----------------|----------------|--------------|
| Pre-heat | 120~150°C | Temperature | 300°C Max. | Pre-heat | 100°C Max. |
| Pre-heat time | 120 sec. Max. | Soldering time | 3 sec. Max. | Pre-heat time | 60 sec. Max. |
| Peak temperature | 240°C Max. | | (one time only) | Solder wave | 260°C Max. |
| Soldering time | 10 sec. Max. | | | Soldering time | 10 sec. Max. |

5. Drive Method

LED is a current operated device, and therefore, requires some kind of current limiting incorporated into the drive circuit. This current limiting typically takes the form of a current limiter resistor placed in series with the LED.

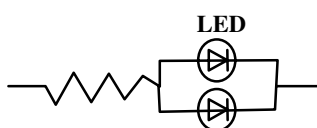
Consider worst case voltage variations that could occur across the current limiting resistor. The forward current should not be allowed to change by more than 40% of its desired value.

Circuit model A



(A) Recommended circuit.

Circuit model B



(B) The difference of brightness between LEDs could be found due to the Vf-If characteristics of LED.

Property of Lite-On Only

6. ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling these LED. All devices, equipment and machinery must be properly grounded.

7. Reliability Test

| Classification | Test Item | Test Condition | Reference Standard |
|--------------------|--|--|---|
| Endurance Test | Operation Life | Ta= Under Room Temperature As Per Data Sheet Maximum Rating *Test Time= 1000HRS (-24HRS,+72HRS)*@20mA. | MIL-STD-750D:1026 (1995) MIL-STD-883D:1005 (1991) JIS C 7021:B-1 (1982) |
| | High Temperature High Humidity Storage | IR-Reflow In-Board, 2 Times Ta= 65±5°C ,RH= 90~95% *Test Time= 1000HRS±2HRS | MIL-STD-202F:103B(1980) JIS C 7021:B-11(1982) |
| | High Temperature Storage | Ta= 105±5°C *Test Time= 1000HRS (-24HRS,+72HRS) | MIL-STD-883D:1008 (1991) JIS C 7021:B-10 (1982) |
| | Low Temperature Storage | Ta= -55±5°C *Test Time=1000HRS (-24HRS,+72H RS) | JIS C 7021:B-12 (1982) |
| Environmental Test | Temperature Cycling | 105°C ~ 25°C ~ -55°C ~ 25°C 30mins 5mins 30mins 5mins 10 Cycles | MIL-STD-202F:107D (1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1010 (1991) JIS C 7021:A-4(1982) |
| | Thermal Shock | IR-Reflow In-Board, 2 Times 105 ± 5°C ~ -55°C ± 5°C 10mins 10mins 10 Cycles | MIL-STD-202F:107D(1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1011 (1991) |
| | Solder Resistance | T.sol= 260 ± 5°C Dwell Time= 10 ± 1secs | MIL-STD-202F:210A(1980) MIL-STD-750D:2031(1995) JIS C 7021:A-1(1982) |
| | IR-Reflow | Ramp-up rate(183°C to Peak) +3°C second max Temp. maintain at 125(±25)°C 120 seconds max Temp. maintain above 183°C 60-150 seconds Peak temperature range 235°C +5/-0°C Time within 5°C of actual Peak Temperature (tp) 10-30 seconds Ramp-down rate +6°C/second max | MIL-STD-750D:2031.2(1995) J-STD-020(1999) |
| | Solderability | T.sol= 235 ± 5°C Immersion time 2±0.5 sec Immersion rate 25±2.5 mm/sec Immersion rate 25±2.5 mm/sec Coverage ≥95% of the dipped surface | MIL-STD-202F:208D(1980) MIL-STD-750D:2026(1995) MIL-STD-883D:2003(1991) IEC 68 Part 2-20 JIS C 7021:A-2(1982) |

8. Others

The appearance and specifications of the product may be modified for improvement without notice.